I Number	Hits	Search Text	DB	Time stamp
L Number	104	polymer and defect and photoresist and mask and expose	USPAT;	2002/06/04 08:26
1	104	and bake	US-PGPUB;	
1		and bake	EPO; JPO;	
			IBM_TDB	
13	26693	((hot adj deionized adj water) ( hot and DIW) (hot adj DI adj	USPAT;	2002/06/04 08:43
13	20030	water ) (hot adj DI water) and rinse and temperature)	US-PGPUB;	- •
		water / (not day by water) and	EPO; JPO;	
			IBM_TDB	
19	26669	((hot adj deionized adj water) ( hot adj DIW) (hot adj DI adj	USPAT;	2002/06/04 11:59
		water) (hot adj DI water) and rinse and temperature)	US-PGPUB;	
			EPO; JPO;	1:
25	104	((hot adj deionized adj water) and rinse and temperature)	IBM_TDB	0000000000000000
			USPAT;	2002/06/04 08:44
			US-PGPUB;	
			EPO; JPO;	
	3	(( hot adj_DIW) and rinse and temperature)	IBM_TDB	0000/00/04 00:45
31			USPAT;	2002/06/04 08:45
			US-PGPUB;	
			EPO; JPO;	
	45	((hot adj DI adj water) and rinse and temperature and	IBM_TDB	2002/06/04 10:12
43			USPAT;	2002/06/04 10:13
1		heat\$?)	US-PGPUB;	
			EPO; JPO;	
			IBM_TDB USPAT;	2002/06/04 11:17
59	8	((hot adj DI ) and deionized and (developer developed) and	US-PGPUB:	2002/00/04 11.17
		photoresist and temperature and ( heat heater) )	EPO; JPO;	
			IBM_TDB	
		(L. L. (D. D.)A() and water and deignized and (developer	USPAT;	2002/06/04 11:19
65	235	(hot and (DI DIW) and water and deionized and (developer	US-PGPUB:	2002/00/01 11:10
		developed) and photoresist and temperature and ( heat	EPO; JPO;	
		heater))	IBM_TDB	
	48	((hot adj deionized adj water) and ( hot adj DIW) (hot adj DI	USPAT;	2002/06/04 13:14
71	40	adj water ) and rinse and temperature)	US-PGPUB;	
		auj water / and mise and temperature/	EPO; JPO;	
	1	development adj related adj defect	IBM_TDB	
77			USPAT;	2002/06/04 13:15
' '	•	4010.00	US-PGPUB;	
			EPO; JPO;	
		·	IBM_TDB	
83	499	development adj defect	USPAT;	2002/06/04 13:15
			US-PGPUB;	
			EPO; JPO;	
			IBM_TDB	2002/06/04 42:42
89	69	(development adj defect) and photoresist	USPAT;	2002/06/04 13:42
			US-PGPUB;	1
			EPO; JPO;	
			IBM_TDB	2002/06/04 13:39
95	1		USPAT	2002/06/04 13:39
96	1	, , , , , , , , , , , , , , , , , , ,		2002/06/04 13:41
97	2	(development adj defect) and photoresist and blob	USPAT; US-PGPUB;	2002/00/04 10.42
			EPO; JPO;	
400			IBM TDB	
	26	(dovelopment adj. defeat) and photoresist and water	USPAT;	2002/06/04 13:43
103	26	(development adj defect) and photoresist and water	US-PGPUB;	
1			EPO; JPO;	
109	499	( (development adj_defect) (post-development adj_defect)	IBM_TDB	'
			USPAT;	2002/06/04 14:02
			US-PGPUB;	
		and photoresist and water )	EPO; JPO;	
			IBM TDB	
1			1,0,,,	

		the transist and mask and evenous?	USPAT;	2002/06/03 16:04
-	0	(polymer and blob) and photoresist and mask and expos&?	US-PGPUB;	2002/00/00 10:04
		and bak&? and develop&? and hea&? and ((deionized adj	EPO; JPO;	
		water) ( hot and DIW)) and rins&?	IBM TDB	
	_	// I will I will be a second and mook and owners??	USPAT:	2002/06/03 16:05
-	0	((polymer and blob) and photoresist and mask and expose?	US-PGPUB;	2002/00/00 10:00
		and bak&? and develop&? and hea&? and ((deionized adj	EPO; JPO;	
		water) ( hot and DIW) )and rins&?)	IBM TDB	
	_		USPAT:	2002/06/03 16:06
-	0	((polymer and blob) and photoresist and mask and expos&?	US-PGPUB;	2002/00/03 10:00
		and bak&? and develop&? and heat&? and ((deionized adj		
		water) ( hot and DIW) )and rins&?)	EPO; JPO;	
			IBM_TDB	2002/06/03 16:10
-	0	((polymer and defect) and photoresist and mask and	USPAT;	2002/00/03 10.10
		expos&? and bak&? and develop&? and heat&? and	US-PGPUB;	
	1	((deionized adj water) ( hot and DIW) )and rins&?)	EPO; JPO;	
			IBM_TDB	0000/06/03 46:09
-	38	(438/727).CCLS.	USPAT;	2002/06/03 16:08
			US-PGPUB;	
			EPO; JPO;	
			IBM_TDB	000000000000000000000000000000000000000
-	0	polymer and defect and photoresist and mask and expos&?	USPAT;	2002/06/03 16:09
		and bak&?	US-PGPUB;	
	:		EPO; JPO;	
			IBM_TDB	00000000000000
-	6	((polymer and defect) and photoresist and mask and expose	USPAT;	2002/06/04 08:39
		and bake and develop and heat and ((deionized adj water) (	US-PGPUB;	
		hot and DIW) )and rinse)	EPO; JPO;	
			IBM_TDB	0000/00/00 40 40
-	0	((polymer and blob) and photoresist and mask and expose	USPAT;	2002/06/03 16:19
		and bake and develop and heat and ((deionized adj water) (	US-PGPUB;	
		hot and DIW) )and rinse)	EPO; JPO;	
			IBM_TDB	0000/00/00 40:00
-	15	(polymer and photoresist and mask and expose and bake	USPAT;	2002/06/03 16:20
		and develop and heat and ((deionized adj water) ( hot and	US-PGPUB;	
		DIW) )and rinse)	EPO; JPO;	
			IBM_TDB	